

Title (en)
METHOD OF MONITORING THE SOLIDIFICATION PROCESS IN CONTINUOUS CASTING

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EP 0384174 A3 19910306 (DE)

Application
EP 90101969 A 19900201

Priority
DE 3905516 A 19890223

Abstract (en)
[origin: EP0384174A2] For trouble-free progress of the casting process in continuous casting, as accurate data as possible on the position and extent of the solidification front within the continuous casting mould surrounded by an electromagnetic moving field are required. <??>The method according to the invention for monitoring the solidification process uses the signals of at least two sensor coils arranged concentrically around the continuous casting mould. The signals are fed to a measuring transducer and processed in an appropriate manner. The arrangement of the sensor coils within the levitation coil generating the moving field is particularly preferred.

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Citation (search report)
• [YD] DE 3049353 A1 19820204 - GEN ELECTRIC [US]
• [A] GB 2061783 A 19810520 - ASEA AB
• [A] US 4030533 A 19770621 - ITOH YASUO, et al
• [A] EP 0098214 A1 19840111 - SIDERURGIE FSE INST RECH [FR]
• [Y] FOUNDRY, Band 13, Nr. 3, März 1980, Zusammenfassung Nr. 51-0321; "Improved system for measuring molten steel level in mold of CC[continious casting] machine", & NKK NEWS, April 1979, 19, (3), 1.3
• [A] PATENT ABSTRACTS OF JAPAN, vol. 9, no. 297 (M-432)[2020], 25. November 1985; & JP-A-60 133 955 (SUMITOMO) 17-07-1985

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